

NANO STRUCTURE FOR ELECTRICAL INTERCONNECT INCLUDING INTEGRATED CIRCUIT MOUNTING

Tech ID: 17325 / UC Case 2004-018-0

ABSTRACT

PATENT STATUS

Country	Type	Number	Dated	Case
United States Of America	Issued Patent	8,610,290	12/17/2013	2004-018
United States Of America	Issued Patent	7,476,982	01/13/2009	2004-018

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OTHER INFORMATION

CATEGORIZED AS

- » **Nanotechnology**
- » Electronics
- » Materials

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